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Announcement of the  
**60<sup>th</sup> Annual**



# DEVICE RESEARCH CONFERENCE

University of California  
Santa Barbara, California

June 24–26, 2002

## CALL FOR PAPERS

Abstract Deadline: February 22, 2002  
Late News Deadline: May 31, 2002





The DRC brings together scientists, engineers, and students to discuss new and exciting breakthroughs and advances in the field of device research. The IEEE Electron Devices Society sponsors the DRC. The conference will be held at the University of California, Santa Barbara, California from Monday, June 24 through Wednesday, June 26, 2002. The DRC and the Electronic Materials Conference (EMC) of TMS will again coordinate activities. The EMC will be held at the same location on Wednesday, June 26 through Friday, June 28, 2002. Device-oriented papers should be submitted to the DRC and materials-oriented papers to the EMC.

### EMERGING TECHNOLOGIES SESSION

A session will be dedicated to new materials, novel devices and emerging technologies. Invited speakers will present the latest developments in promising new devices and device technologies.

### EXPLORATORY DEVICES DISCUSSION SESSION

A limited number of abstracts will be accepted for presentation in a poster and discussion session. The focus is on exploratory device concepts and novel device technologies. Authors who wish for their abstract to be considered for inclusion in this session should consult the DRC Web pages for instructions.

### PAPERS ARE SOLICITED ON A VARIETY OF NOVEL DEVICE STRUCTURES INCLUDING, BUT NOT LIMITED TO THE FOLLOWING:

**Special emphasis:** Actively soliciting papers on micromachined devices, including optical MEMs, BioMEMs, sensors, and actuators.

- Silicon CMOS/BiCMOS
- New Characterization Techniques
- Silicon Scaled and Ultrasmall Devices
- III-V FET & Bipolar Devices
- SOI & 3-D Devices
- Wireless/Microwave Devices
- Millimeter Wave & Ultrafast Devices
- Non-Volatile, Static & Scaled Dynamic Memory
- Optical Sources & Detectors
- Short Wavelength Emitters
- Integrated Optoelectronics
- SiGe, SiGeC & SiC Devices
- High Voltage/High Power Devices
- Wide Bandgap Devices
- Device Modeling
- Sensors and Micromachined Devices
- Quantum Effects & Single Electron Devices
- Nanometer Device Technology
- Novel Magnetic Technology
- Superconducting Devices
- Devices for Displays & Imaging
- Thin Film Transistors
- Vacuum Microelectronics
- Amorphous & Polycrystalline Devices
- Organic Emitters & Transistors
- Low Power Device Technology
- Thin Insulators & Hot Electron Effects
- Reliability

### CALL FOR PAPERS

Authors are requested to send 25 copies of a summary of their paper, together with the IEEE copyright transfer form found in the January issue of IEEE Journals, to Jeff Welser, IBM Microelectronics, Mail Stop E40, 2070 Route 52, Hopewell Junction, NY 12533, USA. A summary sent electronically or by facsimile cannot be accepted. Authors should consult the DRC Web Pages (address listed below) for detailed instructions.

### BEST STUDENT PAPER AWARD

Papers presented by students, based on their own work, are eligible for this annual award. Please identify an abstract as a "Student Paper" in the cover letter when submitting.

### FURTHER INFORMATION

Registration forms and information on accommodations can be obtained from Nadir Dagli, Local Arrangement Chair (information listed on opposite side of this brochure) or the WWW address listed below.

Early registration is encouraged with a reduced registration fee offered as an incentive. Students will also receive a reduced registration fee. Limited travel funds are available to students presenting papers. Further information on student assistance may be obtained by writing to Sanjay Banerjee, General Program Chair (information listed on opposite side of this brochure).

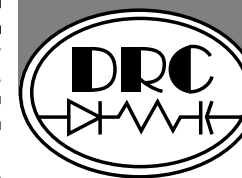
### WORLD WIDE WEB INFORMATION

<http://www.tms.org/Meetings/Specialty/DRC/2002/DRC-2002-Home.html>

## DEVICE RESEARCH CONFERENCE

JUNE 24-26, 2002

UNIVERSITY OF CALIFORNIA • SANTA BARBARA, CALIFORNIA



*All prospective authors/attendees, please complete and return*

- I plan to attend the conference.
- I wish to make a presentation at the conference and have enclosed an abstract.

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